

1.- 8. (Previously canceled)

*✓* 8. (Currently Amended) The colloid silica slurry wherein it does not have a bad influence, such as corrosion, to a silicon wafer and wiring material on a silicon wafer and inhibits growth of microbes, and whereof preserving stability is high because stability of a particle diameters of colloidal particle is superior and using for a long period continuously is possible, and said colloidal silica slurry is comprised by adding hydrogen peroxide 5 to 100 ppm to lowered metal silica slurry, which metal content is 1 ppm or less and produced from silicate ester, and the pH of colloidal silica slurry is 6.0 to 8.0 and content of colloidal silica is 0.05 ~ 50 weight % hydrogen peroxide from 5 to 100 ppm is added and pH is from 6.0 to 8.0.

10. (Canceled)

11. (Canceled)

12. (Canceled)

*✓* 13. (Previously Added) The colloidal silica slurry as claimed in claim 8, wherein pH is from 6.5 to 7.5.

*3* *✓* 14. (Currently Amended) The colloidal silica slurry as claimed in claim 8, wherein additional quantity of said hydrogen peroxide is from 10 to 50 ppm.

*7* *✓* 15. (Previously Added) The colloidal silica slurry as claimed in claim 8, wherein an average particle diameter of said colloidal silica is from 5 to 300 nm.

*5* *✓* 16. (Previously Amended) The colloidal silica slurry as claimed in claim 8, wherein an average particle diameter of said colloidal silica is from 10 to 250 nm.